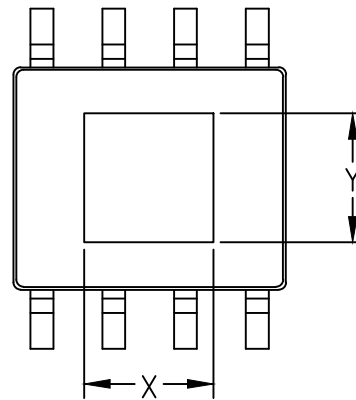
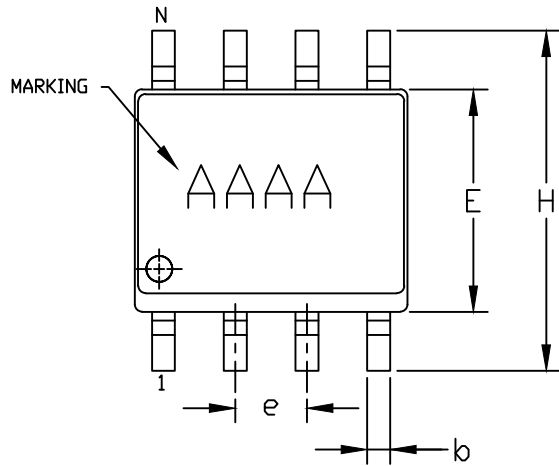


CHANGE DETAILS

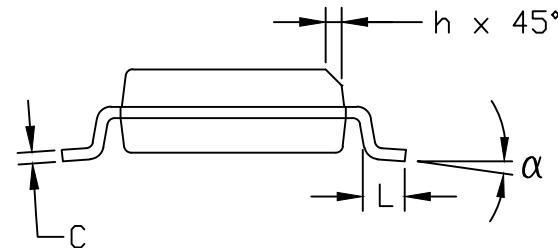
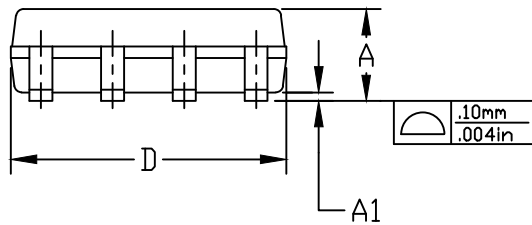
FROM	TO
Current Rev	Added pkgcode S8E-14C

Maxim Integrated	TITLE: PACKAGE OUTLINE, 8L SOIC, .150" EXPOSED PAD		
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DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.056	0.066	1.43	1.68
A1	0.000	0.004	0.00	0.10
b	0.014	0.019	0.35	0.49
C	0.007	0.010	0.19	0.25
D	0.189	0.196	4.80	4.98
e	0.050	BSC	1.27	BSC
E	0.150	0.157	3.81	3.99
H	0.230	0.244	5.81	6.20
h	0.010	0.016	0.25	0.41
L	0.016	0.035	0.41	0.89
α	0°	8°	0°	8°
N	8			

PKG.	X (mm)		Y (mm)	
	MIN	MAX	MIN	MAX
S8E-12	1.98	2.29	1.98	2.29
S8E-14	2.50	3.17	1.87	2.43
S8E-14C	2.50	3.17	1.87	2.43
S8E-15C	1.98	2.29	1.98	2.29



NOTES:

1. D&E DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED .15mm (.006")
3. CONTROLLING DIMENSION: MILLIMETER
4. MEETS JEDEC MS-012 EXCEPT DIMENSION A1.
5. DIMENSIONS X AND Y DEFINE EXPOSED PAD METAL AREA.
6. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.



TITLE:
PACKAGE OUTLINE,
8L SOIC, .150" EXPOSED PAD

APPROVAL
KAI LIU

DOCUMENT CONTROL NO.
21-0111

REV. H 1/1

-DRAWING NOT TO SCALE-